

DATA SHEET

NEC

GaAs INTEGRATED CIRCUIT μ PG2024TQ

GaAs MMIC DPDT SWITCHES FOR 5 GHz BAND WIRELESS LAN

DESCRIPTION

The μ PG2024TQ is a GaAs MMIC DPDT switch for 5 GHz band wireless LAN. Low insertion loss and high handling power contribute to user's system design.

FEATURES

- Operating frequency : $f = 4.8$ to 5.85 GHz
- Low insertion loss : $L_{INS} = 1.2$ dB TYP. @ $f = 4.8$ to 5.85 GHz
- Handling power : $P_{in(0.1\text{ dB})} = +32$ dBm TYP. @ $f = 4.8$ to 5.85 GHz
- Control voltage : $V_{cont} = +2.8$ V/0 V TYP.
- High isolation : ISL (between TX and RX) = 30 dB TYP. @ $f = 5.2$ GHz
ISL (between ANT1/ANT2 and RX/TX) = 25 dB TYP. @ $f = 5.2$ GHz
- Input/output return loss : $RL_{in}/RL_{out} = 20$ dB TYP. @ $f = 4.8$ to 5.85 GHz
- Switching speed : $t_{SW} = 20$ ns TYP. @ t_{RISE}/t_{FALL} (10/90% RF)
- High-density surface mounting : 10-pin plastic TSON package ($2.30 \times 2.55 \times 0.60$ mm)

APPLICATION

- 5 GHz band wireless LAN (IEEE802.11a)

★ ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μ PG2024TQ-E1	μ PG2024TQ-E1-A	10-pin plastic TSON (Pb-Free)	2024	<ul style="list-style-type: none">Embossed tape 8 mm widePin 5, 6 face the perforation side of the tapeQty 3 kpcs/reel

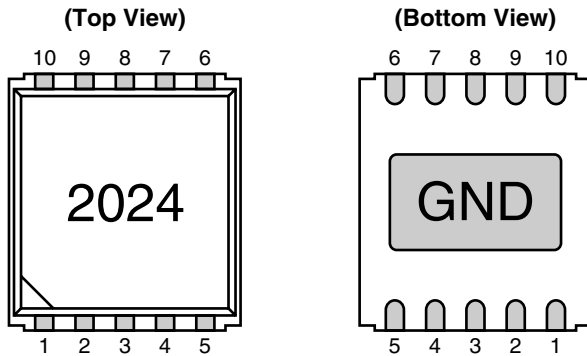
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: μ PG2024TQ

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PIN CONNECTIONS



Pin No.	Pin Name
1	TX
2	V _{cont1}
3	V _{cont2}
4	GND
5	RX
6	ANT1
7	V _{cont3}
8	V _{cont4}
9	GND
10	ANT2

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Control Voltage	V _{cont}	-6.0 to +6.0 ^{Note 1}	V
Input Power	P _{in}	+36	dBm
Total Power Dissipation	P _{tot}	0.15 ^{Note 2}	W
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-65 to +150	°C

Notes 1. Within the condition of $|V_{cont1} - V_{cont2}| \leq 6.0$ V

2. Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB, T_A = +85°C

★ **RECOMMENDED OPERATING RANGE (T_A = +25°C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Control Voltage (High)	V _{cont (H)}	2.7	2.8	3.3	V
Control Voltage (Low)	V _{cont (L)}	-0.2	0	+0.2	V
Operating Frequency	f	4.8	-	5.85	GHz
Operating Ambient Temperature	T _A	-40	+25	+85	°C

★ ELECTRICAL CHARACTERISTICS

(TA = +25°C, Vcont = 2.8 V/0 V, Zo = 50 Ω, DC block capacitor = 2 pF, each port, on the below TRUTH TABLE, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{INS}	f = 4.9 GHz	–	1.2	1.5	dB
		f = 5.2 GHz	–	1.2	1.5	
		f = 5.8 GHz	–	1.5	1.7	
Isolation (Between TX and RX)	ISL	f = 4.9 GHz	20	25	–	dB
		f = 5.2 GHz	25	30	–	
		f = 5.8 GHz	20	25	–	
Input Return Loss	RL _{in}	f = 4.9 GHz	10	20	–	dB
		f = 5.2 GHz	10	20	–	
		f = 5.8 GHz	7	20	–	
Output Return Loss	RL _{out}	f = 4.9 GHz	10	20	–	dB
		f = 5.2 GHz	10	20	–	
		f = 5.8 GHz	7	20	–	
0.1 dB Gain Compression Input Power	P _{in (0.1 dB)}	f = 4.9 GHz	30	33	–	dBm
		f = 5.2 GHz	30	32	–	
		f = 5.8 GHz	30	32	–	
Switching Speed	t _{sw}	t _{RISE} /t _{FALL} (10/90% RF)	–	20	–	ns
Control Current	I _{cont}		–	0.5	–	μA
Input 3rd Order Intercept Point	IIP ₃		–	50	–	dBm

STANDARD CHARACTERISTICS FOR REFERENCE

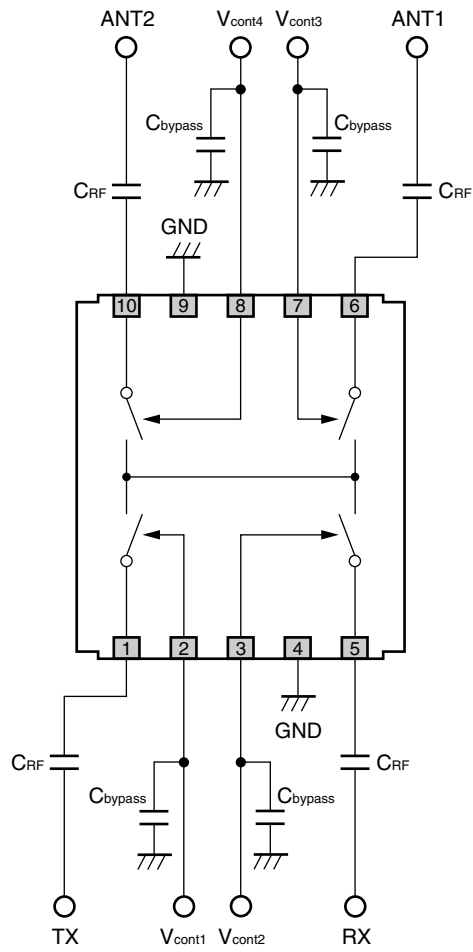
(TA = +25°C, Vcont = 2.8 V/0 V, Zo = 50 Ω, DC block capacitor = 2 pF, each port, on the below TRUTH TABLE, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Isolation (Between ANT1/ANT2 and RX/TX)	ISL	f = 4.9 GHz	–	22	–	dB
		f = 5.2 GHz	–	25	–	
		f = 5.8 GHz	–	21	–	

TRUTH TABLE

V _{cont1}	V _{cont2}	V _{cont3}	V _{cont4}	PASS
Low	High	High	Low	ANT1-RX
High	Low	Low	High	ANT2-TX
High	Low	High	Low	ANT1-TX
Low	High	Low	High	ANT2-RX

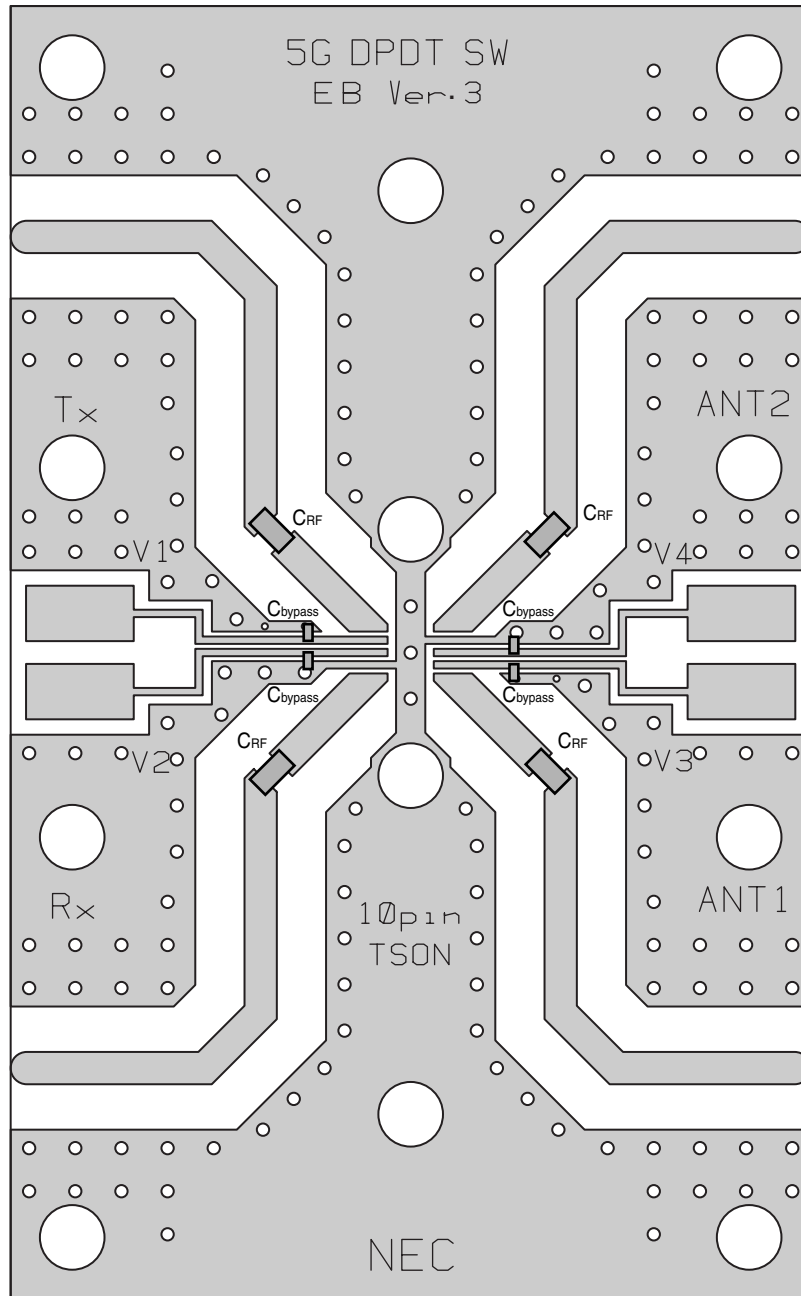
TEST CIRCUIT



Remark C_{RF} : 2 pF
 C_{bypass} : 1 000 pF

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

★ ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

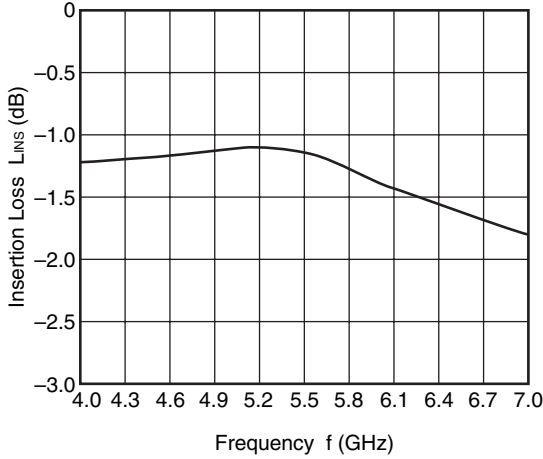


USING THE NEC EVALUATION BOARD

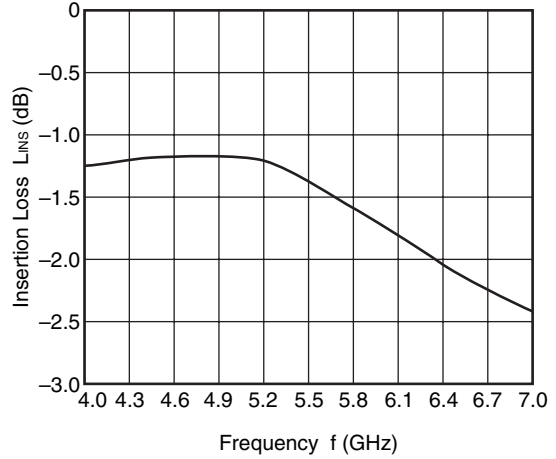
Symbol	Form	Rating	Part Number	Manufacturer
CRF	Chip Capacitor	2 pF	GRM36CK020C50PB	muRata
Cbypass	Chip Capacitor	1 000 pF	GRP033B11C102KD01E	muRata
-	PC Terminal	-	A2-2PA-2.54DSA	Hirose
-	RF Connector	-	142-0721-821	Johnson
-	PWB	-	RO4003 (t = 0.51 mm)	Rogers

★ **TYPICAL CHARACTERISTICS** ($T_A = +25^{\circ}\text{C}$, $V_{\text{cont}} = 2.8 \text{ V}$ / V , $Z_0 = 50 \Omega$, DC block capacitor = 2 pF using test fixture, unless otherwise specified)

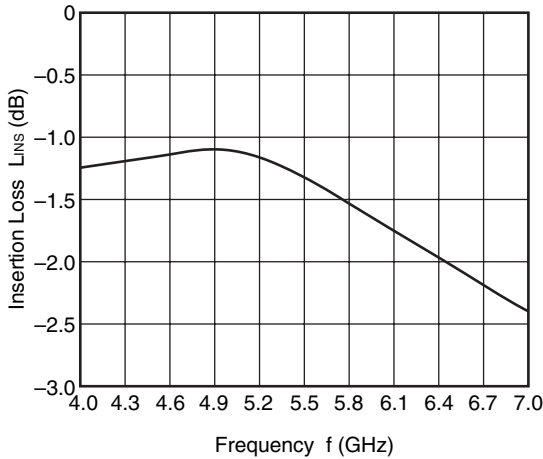
TX-ANT1 INSERTION LOSS vs. FREQUENCY
(When TX-ANT1 is ON)



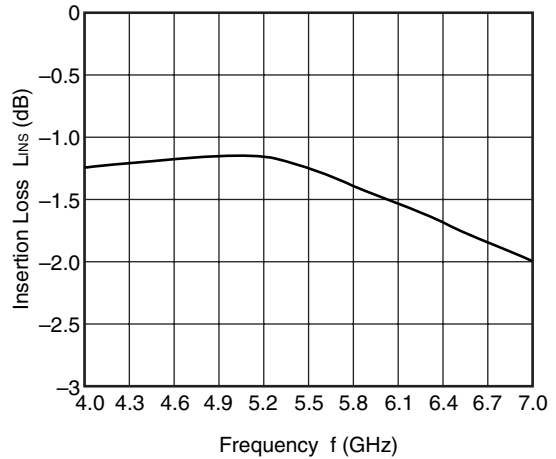
ANT1-RX INSERTION LOSS vs. FREQUENCY
(When ANT1-RX is ON)



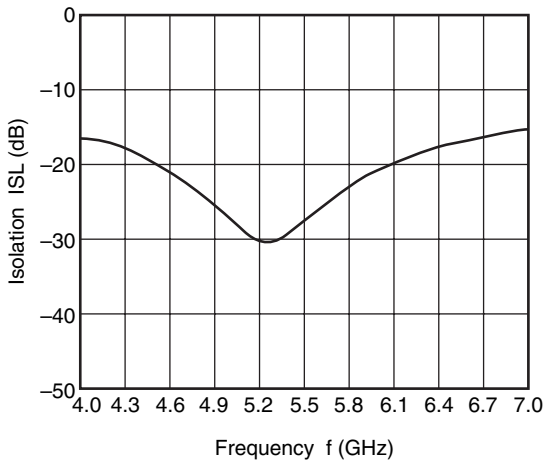
TX-ANT2 INSERTION LOSS vs. FREQUENCY
(When TX-ANT2 is ON)



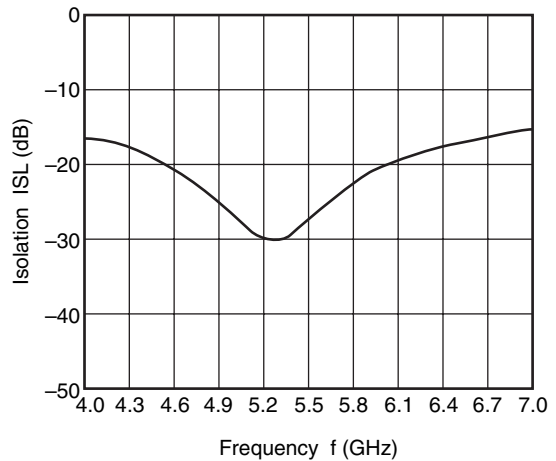
ANT2-RX INSERTION LOSS vs. FREQUENCY
(When ANT2-RX is ON)



RX-TX ISOLATION vs. FREQUENCY
(When ANT2-RX is ON)

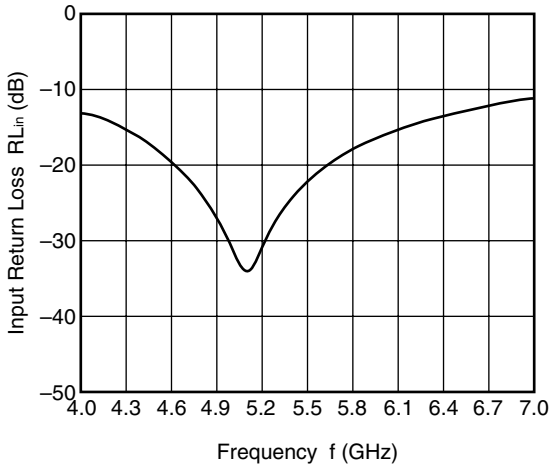


TX-RX ISOLATION vs. FREQUENCY
(When TX-ANT1 is ON)

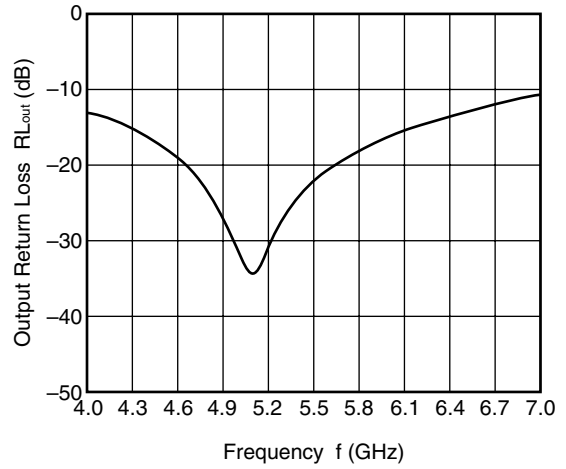


Remark The graphs indicate nominal characteristics.

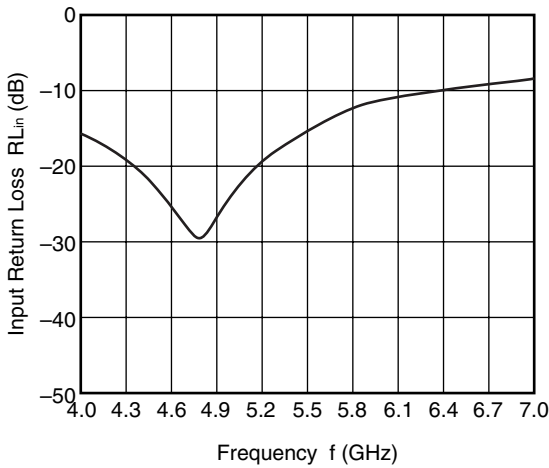
TX-ANT1 INPUT RETURN LOSS vs. FREQUENCY
(When TX-ANT1 is ON)



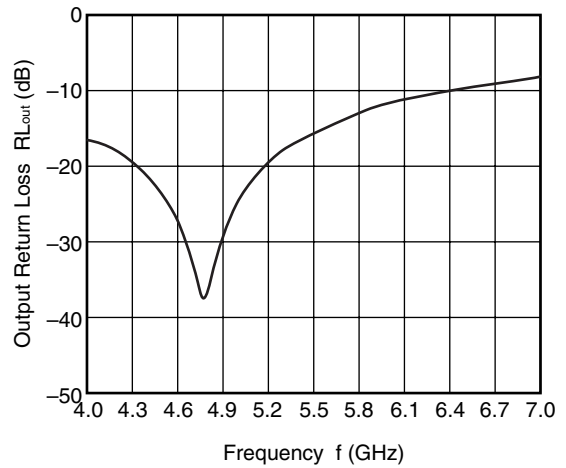
TX-ANT1 OUTPUT RETURN LOSS vs. FREQUENCY
(When TX-ANT1 is ON)



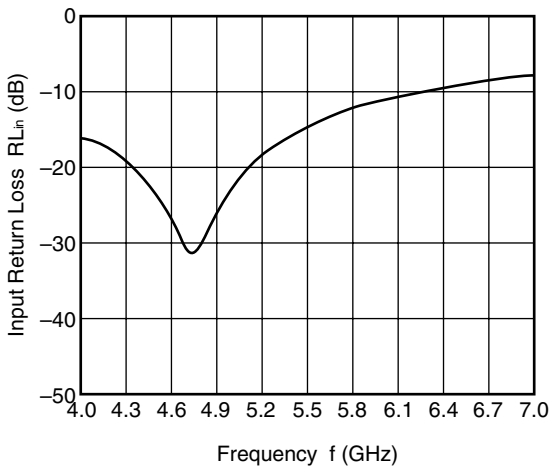
TX-ANT2 INPUT RETURN LOSS vs. FREQUENCY
(When TX-ANT2 is ON)



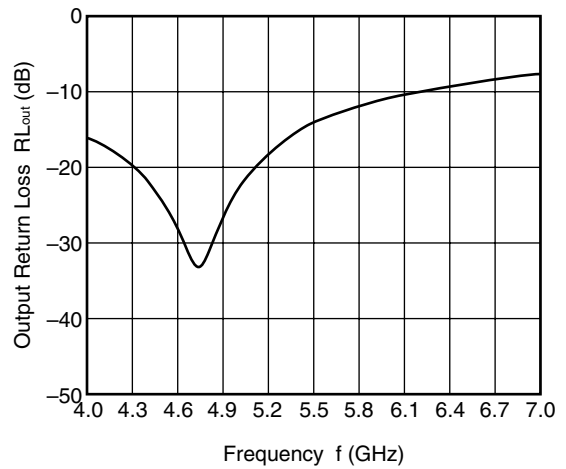
TX-ANT2 OUTPUT RETURN LOSS vs. FREQUENCY
(When TX-ANT2 is ON)



ANT1-RX INPUT RETURN LOSS vs. FREQUENCY
(When ANT1-RX is ON)

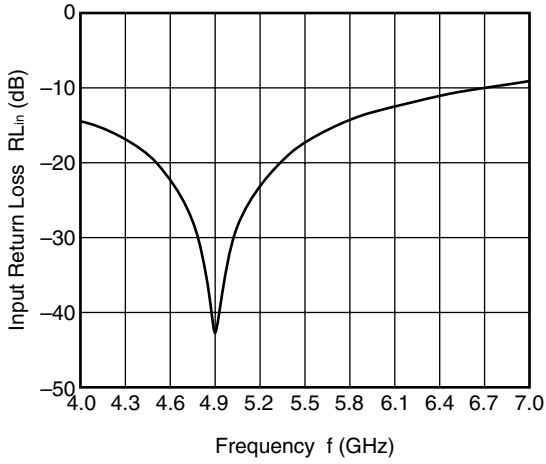


ANT1-RX OUTPUT RETURN LOSS vs. FREQUENCY
(When ANT1-RX is ON)

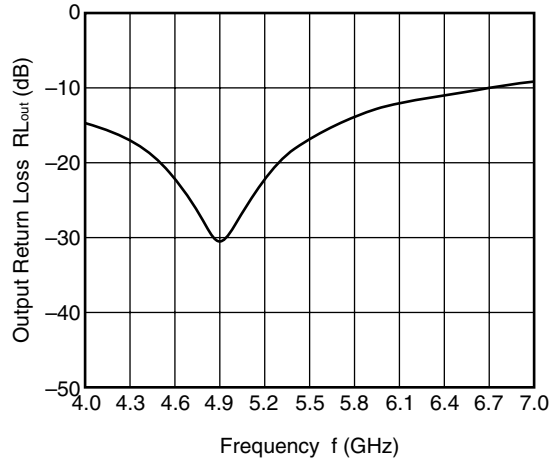


Remark The graphs indicate nominal characteristics.

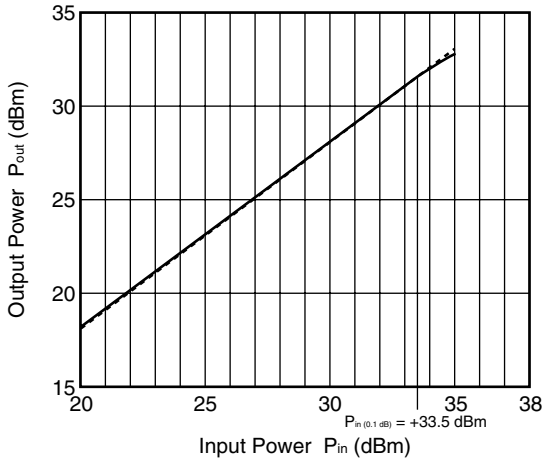
ANT2-RX INPUT RETURN LOSS vs. FREQUENCY
(When ANT2-RX is ON)



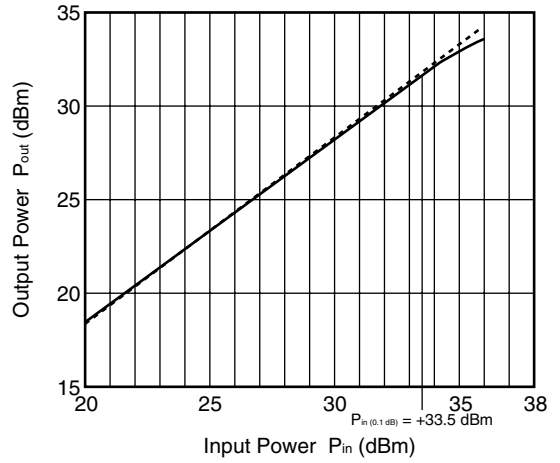
ANT2-RX OUTPUT RETURN LOSS vs. FREQUENCY
(When ANT2-RX is ON)



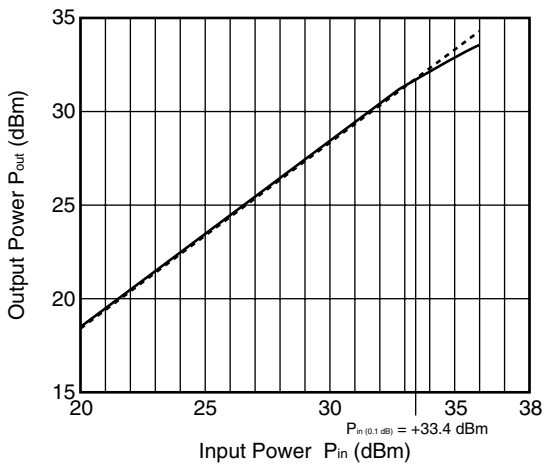
4.9 GHz OUTPUT POWER vs. INPUT POWER



5.2 GHz OUTPUT POWER vs. INPUT POWER



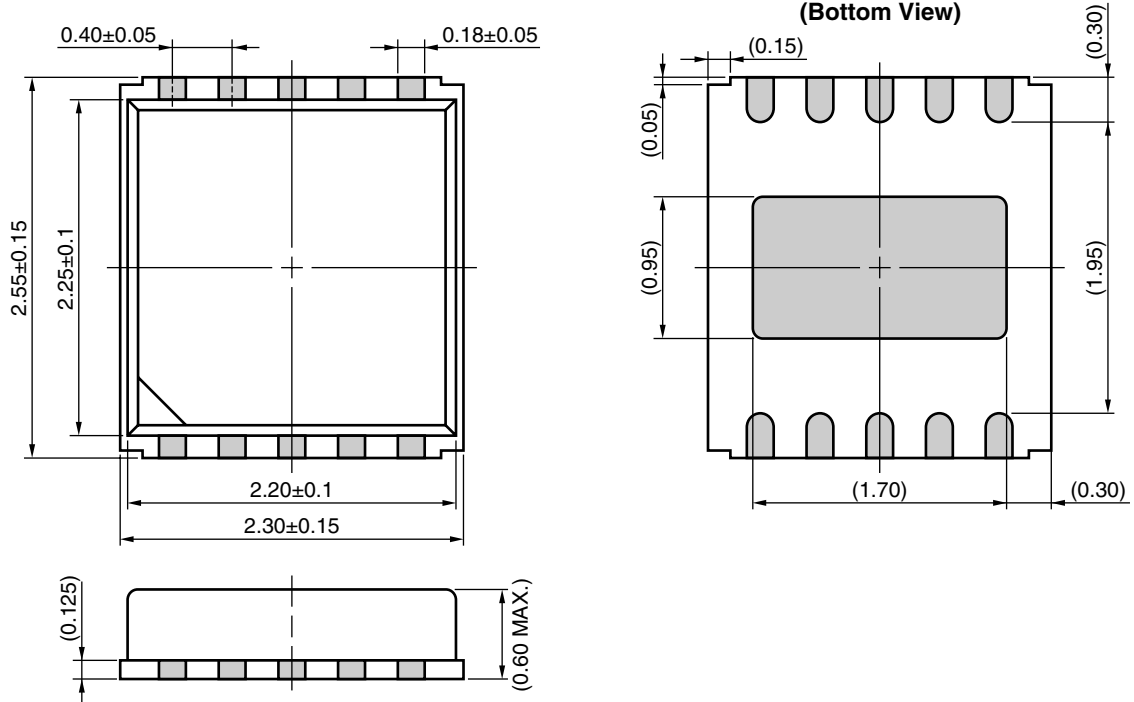
5.8 GHz OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

10-PIN PLASTIC TSON (UNIT: mm)



Remark () : Reference value

★ **RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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- M8E 00.4-0110

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► For further information, please contact

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